ME6980ED/ME6980ED-G

Dual N-Channel 20V(D-S) Enhancement Mode Mosfet

GENERAL DESCRIPTION

The ME6980ED Dual N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

- $R_{DS(ON)} \leqq 14.5m\Omega @ V_{GS}=4.5V$
- $R_{DS(ON)} \leqq 15m\Omega @ V_{GS}=4.0V$
- $R_{DS(ON)} \leqq 17m\Omega @ V_{GS}=3.1V$
- $R_{DS(ON)} \leqq 20m\Omega @ V_{GS}=2.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

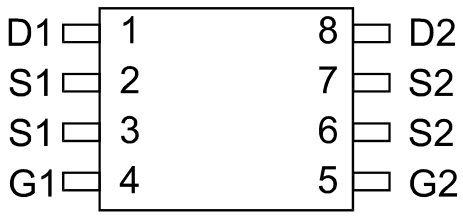
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch
- DSC

PIN CONFIGURATION

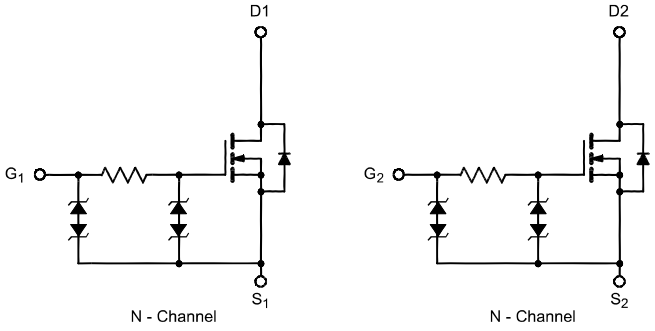
(TSSOP-8)

Top View



Ordering Information: ME6980ED (Pb-free)

ME6980ED-G (Green product-Halogen free)



*Typical value by design

Absolute Maximum Ratings (T_A=25℃ Unless Otherwise Noted)

Parameter		Symbol	Maximum	Unit
Drain-Source Voltage		V_{DSS}	20	V
Gate-Source Voltage		V_{GSS}	±12	V
Continuous Drain Current(tJ=150℃)	T_A=25℃	I_D	7.3	A
	T_A=70℃		5.9	
Pulsed Drain Current		I_{DM}	29	A
Maximum Power Dissipation	T_A=25℃	P_D	1.3	W
	T_A=70℃		0.8	
Operating Junction Temperature		T_J	-55 to 150	℃
Thermal Resistance-Junction to Ambient*		$R_{\theta JA}$	100	℃/W

* The device mounted on 1in^2 FR4 board with 2 oz copper

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Electrical Characteristics (T_A=25℃ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	20			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	0.6		1.2	V
I_{GSS}	Gate Leakage Current	V_{DS}=0V, V_{GS}=±12V			±10	uA
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=20V, V_{GS}=0V			1	μA
$R_{DS(ON)}$	Drain-Source On-State Resistance [a]	V_{GS}=4.5V, I_D=5A		12	14.5	mΩ
		V_{GS}=4V, I_D= 5A		12.5	15	
		V_{GS}=3.1V, I_D= 5A		13.5	17	
		V_{GS}=2.5V, I_D= 5A		16	20	
V_{SD}	Diode Forward Voltage	I_S=10A, V_{GS}=0V		0.9	1.2	V
DYNAMIC						
Qg	Total Gate Charge	V_{DS}=16V, V_{GS}=10V, I_D=10A		36		nC
Qg	Total Gate Charge	V_{DS}=16V, V_{GS}=4.5V, I_D=10A		19		
Qgs	Gate-Source Charge			3.2		
Qgd	Gate-Drain Charge			7.4		
Ciss	Input Capacitance	V_{DS}=25V, V_{GS}=0V,f=1MHz		365		pF
Coss	Output Capacitance			123		
Crss	Reverse Transfer Capacitance			37		
$t_{d(on)}$	Turn-On Delay Time	V_{DD}=10V, R_L =2Ω I_D=5A, V_{GEN}=4V R_G=10Ω		0.8		μs
t_r	Turn-On Rise Time			1.1		
$t_{d(off)}$	Turn-Off Delay Time			4.6		
t_f	Turn-Off Fall Time			2.3		

Notes: a. pulse test: pulse width≦ 300us, duty cycle≦ 2%,Guaranteed by design, not subject to production testing.

Matsuki reserves the right to improve product design, functions and reliability without notice.

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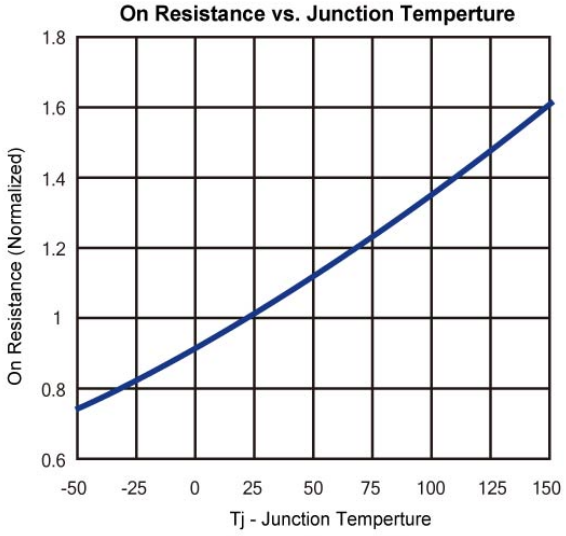
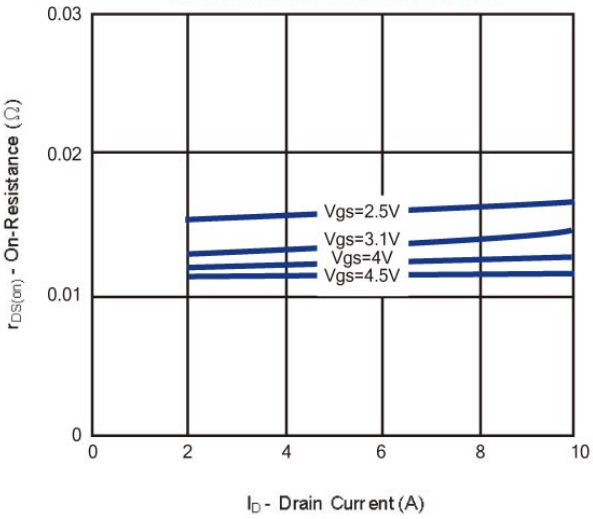
Typical Characteristics (T_J =25℃ Noted)

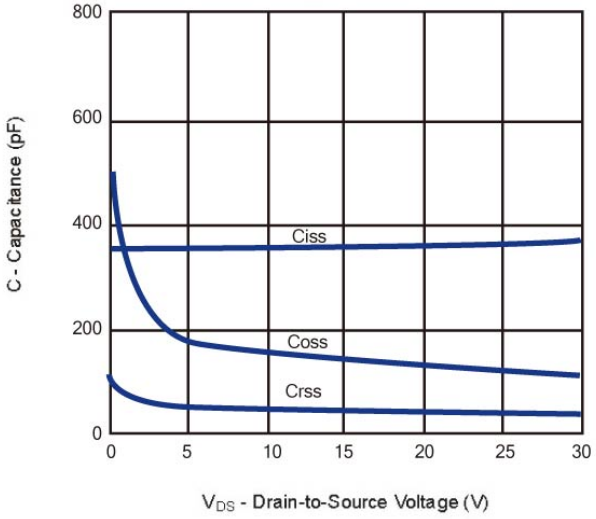
On Resistance vs. Junction Temperture



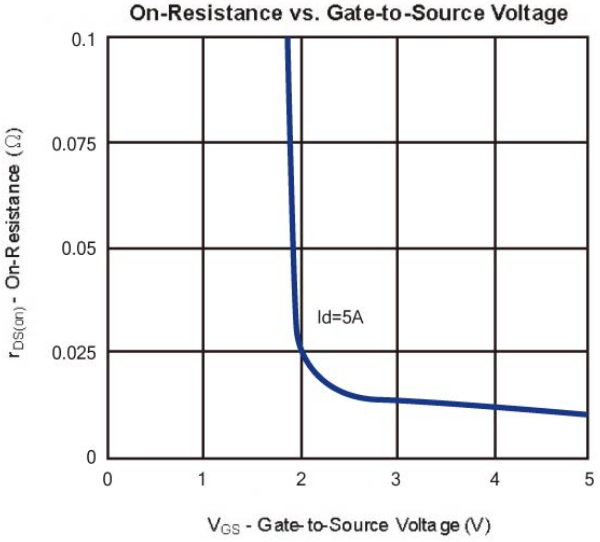
On-Resistance vs. Drain Current



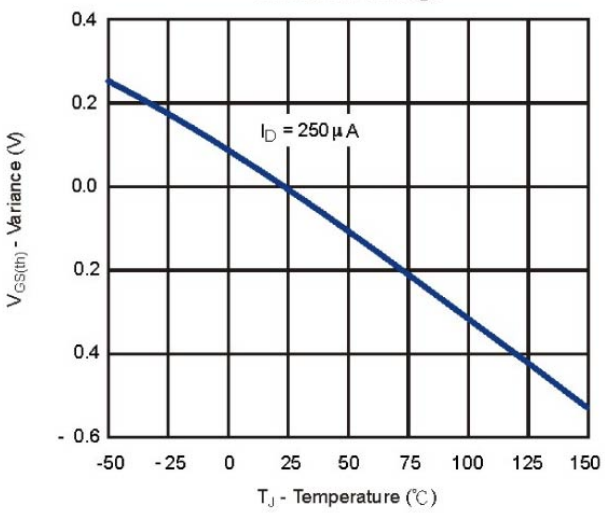
Capacitance



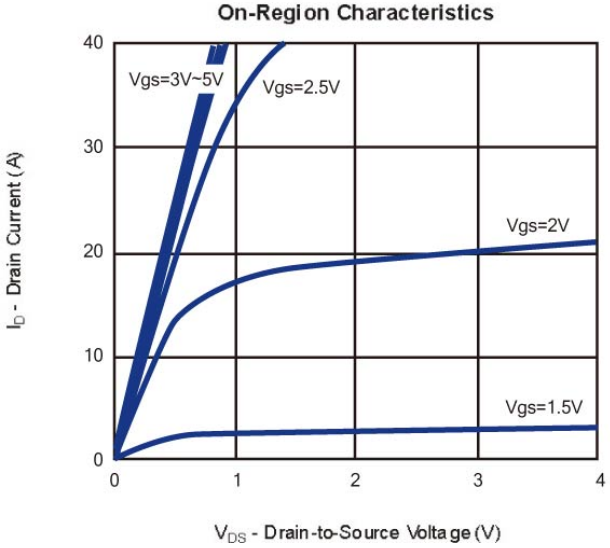
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



On-Region Characteristics



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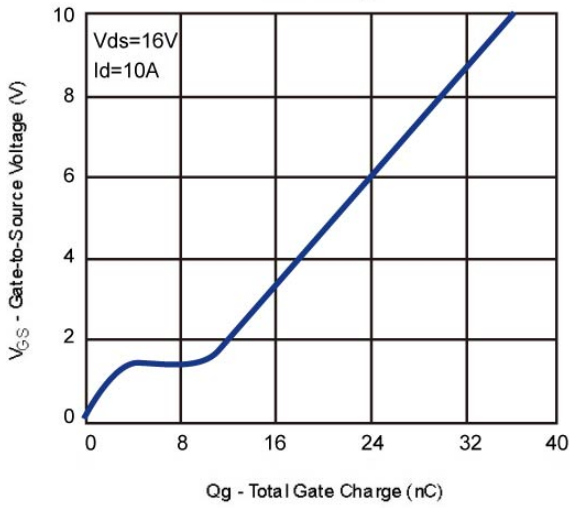
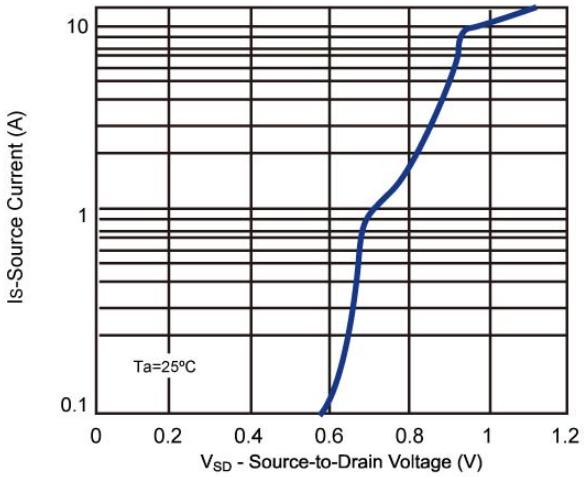
Typical Characteristics (T_J =25℃ Noted)

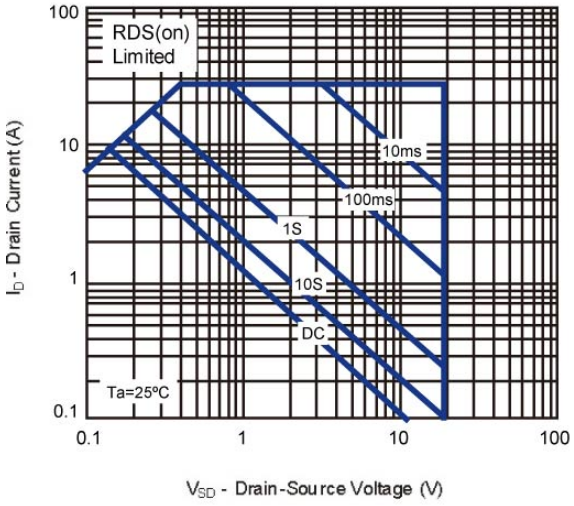
Gate Charge



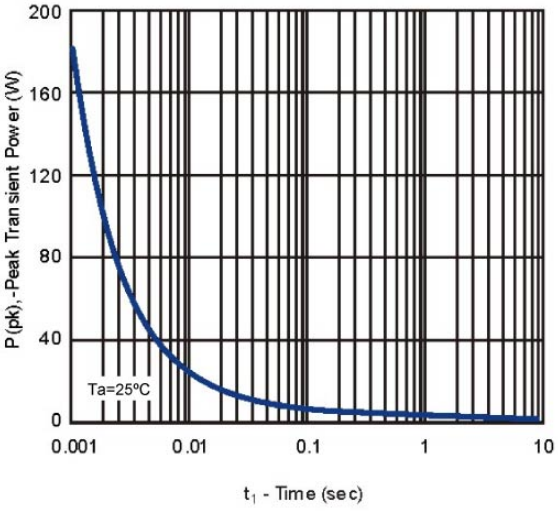
Body-diode characteristics



Maximum Forward Biased Safe Operating Area



Single Pulse Maximum Power Dissipation



Normalized Thermal Transient Impedance, Junction-to-Ambient